

Disco DFG850

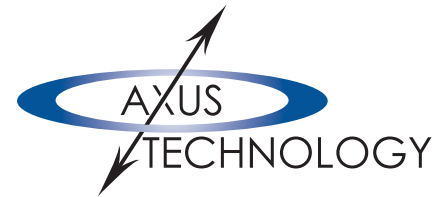


Disco DFG850 system features two air bearing grind spindles, a rotating table with three rotating vacuum wafer chucks, and robotic load/unload operation. This provides high-quality ultra- thin grinding for applications including 3D integration, BSI, bonded wafers, IC slim cards, and more.

OPTIONS AVAILABLE

Temperature control system for stabilizing process results

Vacuum system



Your source for leading-edge surface processing solutions

FEATURES

- Grinds wafers 100 - 200mm
- In-feed grinding with wafer rotation
- Two independently adjustable spindles
- Porous vacuum wafer chucks
- 2-point contact in-process thickness gauging
- 200mm diamond grinding wheel
- 2 cassettes for load/unload